

In the Specification:

This application is a continuation of U.S. Application No. 10/102,040, filed March 19, 2002, which is ~~This application is a continuation application of U.S. Patent Application Serial No. 09/441,712, filed November 16, 1999, Patent No. 6,358,388, entitled A PLATING SYSTEM WORKPIECE SUPPORT HAVING WORKPIECE ENGAGING ELECTRODE WITH DISTAL CONTACT PART AND DIELECTRIC COVER, which is a continuation of U.S. patent application Serial No. 08/988,333, filed September 30, 1997, Patent No. 5,985,126, entitled SEMICONDUCTOR PLATING SYSTEM WORKPIECE SUPPORT HAVING WORKPIECE-ENGAGING ELECTRODES WITH DISTAL CONTACT PART AND DIELECTRIC COVER, which is a continuation-in-part of U.S. patent application Serial No. 08/680,057, filed July 15, 1996, Patent No. 5,980,706.~~